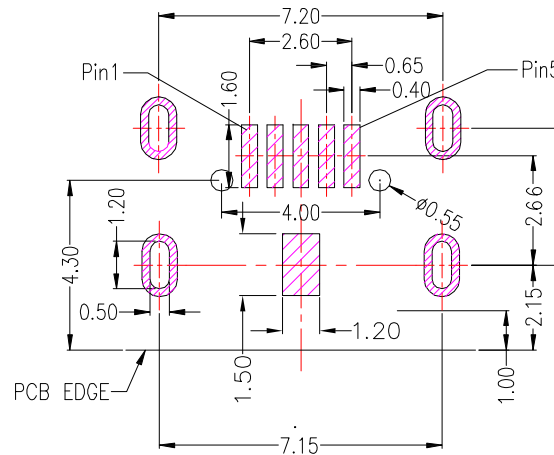
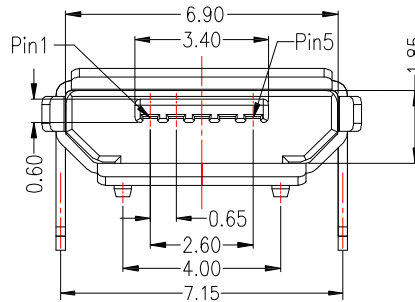
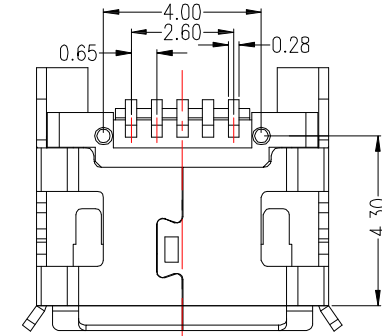
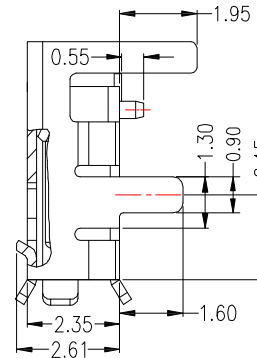
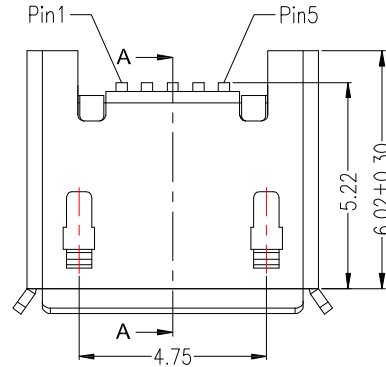


SECTION A-A



P.C.B LAYOUT MOUNTING PATTERN

NOTES:

MATERIAL:

- 1.1 HOUSING: LCP,UL94V-0
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: BRASS

Finish:

- 2.1 Contact: Plated Gold in Mating Area ;  
Gold Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A (PIN1&5) MAX,1.0 A (PIN2&3&4) MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu 11/17/17  
CHECKED BY: Jacky Chen 11/17/17  
APPROVED BY: Tony Kao 11/17/17

MAT'L  
FINISH  
SCALE 1 : 1  
SHEET NO. 1 of 1

TITLE CONNECTOR  
MODLE MICRO USB B TYPE SHELL DIPx4: 7.15 ; W/embossing  
DWG NO. MRUSB-5B-ED7NI-S347  
PART NO. MRUSB-5B-ED7NI-S347

SIZE A4  
VER A3

| ITEM NO. | DESCRIPTION    | DRAWN | DATE   |
|----------|----------------|-------|--------|
| 3        | 更新PCB LAYOUT   | Jack  | 111717 |
| 2        | 更新PCB LAYOUT尺寸 | Jack  | 062617 |
| 1        | 新增PIN定義        | Jack  | 080816 |